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#### Materials science communication

# Fabrication and characterization of silicon-based ceramic/aluminum nitride as thermally conductive hybrid filler in silicone rubber composite

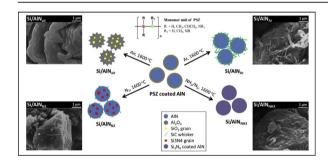


Hsien-Tang Chiu <sup>a,\*</sup>, Tanapon Sukachonmakul <sup>a</sup>, Chen-Hao Wang <sup>a</sup>, Karnthidaporn Wattanakul <sup>b</sup>, Ming-Tai Guo <sup>a</sup>, Yu-Hsiang Wang <sup>a</sup>

#### HIGHLIGHTS

- Si/AlN fillers were fabricated by pyrolysis of PSZ/AlN at 1600 °C in air, Ar, N<sub>2</sub> and NH<sub>3</sub>.
- Pyrolysis in various atmospheres resulted in different morphology of Si/AIN fillers.
- Si/AlN which was pyrolysis in Ar or NH<sub>3</sub> can be used as thermally conductive fillers.

#### G R A P H I C A L A B S T R A C T



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#### ABSTRACT

Silicon-based ceramics and aluminum nitride (Si/AlN) were fabricated by pyrolysis of polysilazane (PSZ) coated AlN at 1600 °C in air, Ar,  $N_2$  and  $NH_3$  atmospheres. The results from XRD, XPS and SEM/EDS revealed the existence of crystalline phase of Si-based ceramics on AlN particles including  $SiO_2$  in  $Si/AlN_{air}$ , SiC whisker in  $Si/AlN_{Ar}$ , SiC whisker/ $Si_3N_4$  grain in  $Si/AlN_{N_2}$ , and  $Si_3N_4$  ceramics in  $Si/AlN_{NH_3}$ . It was found that the thermal conductivity of silicone rubber filled with Si/AlN hybrid fillers which were fabricated in Ar and  $NH_3$ , was improved. This might be due to the existence of nanoscale SiC whiskers and a thermal conductive layer of  $Si_3N_4$  on  $Si/AlN_{Ar}$  and  $Si/AlN_{NH_3}$  surface, respectively. Thus, it can be suggested that Si/AlN hybrid fillers, especially for the case of  $Si/AlN_{(Ar\ and\ NH_3)}$ , can be applicable to use as thermally conductive fillers. This work may have found to be an alternative way to improve thermal conductivity, but more work needs to be done to really achieve significant improvement.

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#### 1. Introduction

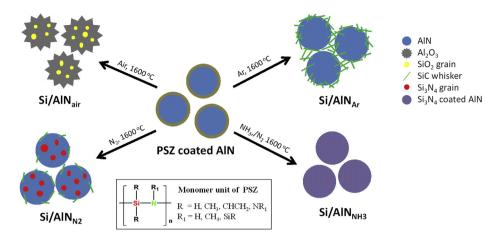
Thermally conductive and electrically insulating polymer composites have received extensive attention in electronic devices because these composites can dissipate heat and prevent overheating in electronic devices during operation. Nowadays, these composites have been used in many applications including (1) thermal interface materials between heat dissipating system and

<sup>&</sup>lt;sup>a</sup> Department of Material Science and Engineering, National Taiwan University of Science and Technology, Taipei 106, Taiwan

<sup>&</sup>lt;sup>b</sup> Department of Polymer Engineering Mechanical Engineering Technology, College of Industrial Technology, King Mongkut's University of Technology North Bangkok, Bangkok 10800, Thailand

<sup>\*</sup> Corresponding author.

E-mail address: hchiu@mail.ntust.edu.tw (H.-T. Chiu).



Scheme 1. A route for a fabrication of Si/AlN hybrid fillers via pyrolysis of PSZ coated AlN at 1600 °C in various atmospheres.

chips in microelectronic devices [1], (2) encapsulating materials in silicon integrated circuits [2] and solar photovoltaic cells [3], (3) plastic heat sink in LED light bulbs [4] and (4) mobiles phone shell [5] and so on. Typically, thermally conductive composites are made of polymer matrix filled with thermally conductive fillers. It is acknowledged that polymers such as polycarbonate and epoxy resin possess low dielectric constant, low weight, high strength, high rigidity and high impact resistance [2,5,6]. In addition, silicone rubber and ethylene vinyl acetate possess high electrical resistivity, excellent flexibility, high damping capacity and high resistance to permanent deformation [1,3]. It is well known that polymer composites can be designed to have desirable properties by addition of specific hybrid fillers into the polymer composites [7,8]. Generally, the thermal conductivity of polymers is very low; therefore, the use of high intrinsically thermally conductive and electrically insulating ceramic, for example; AIN, silicon nitride (Si<sub>3</sub>N<sub>4</sub>) and silicon carbide (SiC) as fillers, can obviously enhance the thermal conductivity of the thermally conductive polymer composites.

PSZ is a preceramic polymer consisting of silicon, nitrogen, oxygen and, in certain case, carbon [9]. More interestingly, PSZ is a versatile material as it is compatible and can be applied with inorganic materials both in metals and ceramics. In addition, PSZ has been extensively used in coating, blending even in dip-coating applications [9,10]. It is interesting to note that pyrolysis of PSZ at the temperature higher than 700 °C in various atmospheres could convert polymeric structure of PSZ into amorphous phase of Si–O–N–C ceramics [10,11], and form binary phase of crystalline silicon oxide (SiO<sub>2</sub>), Si<sub>3</sub>N<sub>4</sub>, SiC ceramics at the temperature around 1400–1600 °C [9–12].

In the present work, the pyrolysis of PSZ coated AlN at the temperature of 1600  $^{\circ}$ C in air, Ar, N<sub>2</sub> and NH<sub>3</sub> atmospheres were accomplished in order to fabricate hybrid fillers of AlN and Si-based ceramics, which are abbreviated hereafter as Si/AlN<sub>air</sub>, Si/AlN<sub>N2</sub> and Si/AlN<sub>NH3</sub>, respectively. Then, characterizations of Si/AlN hybrid fillers were investigated to identify and evaluate the effect of pyrolysis at different atmospheres on hybrid fillers. After that, the thermal conductivity of silicone rubber filled Si/AlN hybrid fillers was observed.

#### 2. Experimental

A route for the fabrication of Si/AlN<sub>(air, Ar, N2 and NH3)</sub> hybrid fillers was shown in Scheme 1. First, AlN with a particle size of 5  $\mu$ m was dipped and stirred in PSZ solution (AlN:PSZ = 2:1 w/w) at room temperature for 1 h, then filtered and heated at 180 °C for 24 h to

allow crosslinking of PSZ film on AlN surface. The pyrolysis of PSZ coated AIN in air, Ar, N<sub>2</sub> and NH<sub>3</sub> atmospheres was carried out by using tube furnace with the heating rate of 3  $^{\circ}$ C min<sup>-1</sup> to the temperature of 1600 °C then dwell of about 2 h, finally cooling with the rate of 10 °C min<sup>-1</sup> to room temperature (except Si/AlN<sub>NH3</sub>, which was heated under NH<sub>3</sub> up to 800 °C and change to N<sub>2</sub> with dwell time 1 h, then the rest was the same as pyrolysis in N2). After that, silicone rubber was compounded with hybrid fillers at the filler content of 56 wt% in two roll mixing mill and compression molded at 160 °C with a pressure of 10 MPa for 20 min in an automatic hot press machine. Crystallinity of Si/AlN hybrid fillers was performed on X-ray diffractometer (XRD) (D2 phaser) using a monochromatic Cu Kα radiation. X-ray photoelectron spectroscopy (XPS) (ESCALAB 250) was used to analyze elemental composition and chemical state of the elements. Energy-dispersive X-ray spectroscopy (EDS) and Field emission-scanning electron microscopic (FE-SEM) observation of hybrid fillers were performed on a JEOL JSM-6500F operated at a voltage of 20 kV. Thermal conductivity of the composites was measured triplicate in each sample using a Hot Disk Thermal Analyzer (Hot Disk AB).

#### 3. Results and discussion

Surface morphology of untreated AlN and Si/AlN hybrid fillers was observed by FE-SEM as shown in Fig. 1 and Fig. S1. EDS analysis was also performed to determine the distribution of Si-based ceramics on hybrid fillers as shown in Support Information Fig. S2 and Table S1. Untreated AlN revealed a clean and smooth surface, while Si/AlNair exhibited a fracture on AlN particle with a smooth grainlike surface. In addition, it has been reported that Si/AlNair particle was expanded due to a lot of nitrogen gas was evolved from inside AIN during the oxidation reaction and results in the increase in gas pressure around the AIN grains, then cause the formation of expansive cracks throughout AIN particle [13]. Moreover, EDS results revealed that SiO<sub>2</sub> was partly distributed on AlN surface. However, for the case of Si/AlN<sub>Ar</sub>, a well-distributed whiskers with a diameter around 50-100 nm was observed on the surface of Si/ AlN<sub>Ar</sub>. Meanwhile, Si/AlN<sub>N2</sub> exhibited the appearance of whiskers and grains on the surface of hybrid filler. It has been reported that pyrolysis of PSZ under Ar can convert PSZ into SiC whisker [14], whereas pyrolysis under N2 would convert PSZ into both SiC whisker and irregular shape of  $Si_3N_4$  [15]. Besides, it was found that the surface morphology of Si/AlN<sub>NH3</sub> showed a sharp polygon surface. These observations suggested that pyrolysis in various atmospheres resulted in different morphology of Si/AlN hybrid fillers.

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